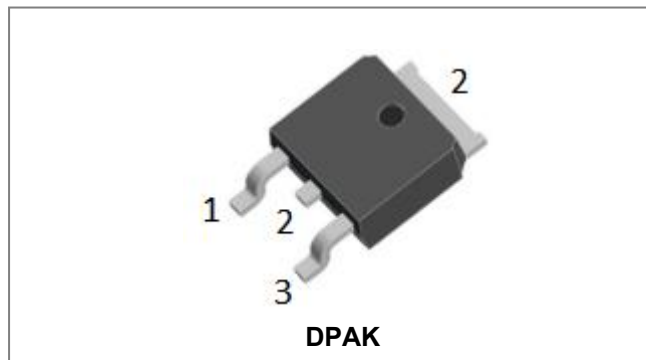


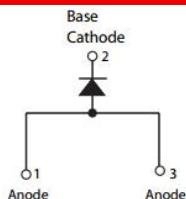
SDD660 STANDARD RECTIFIER



Features

- Glass Passivated Die Construction
- Ideally Suited for Automatic Assembly
- Low Forward Voltage Drop
- Low Power Loss
- Built Strain Relief
- Plastic Case Material has UL Flammability Classification Rating 94V-0
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Mechanical data

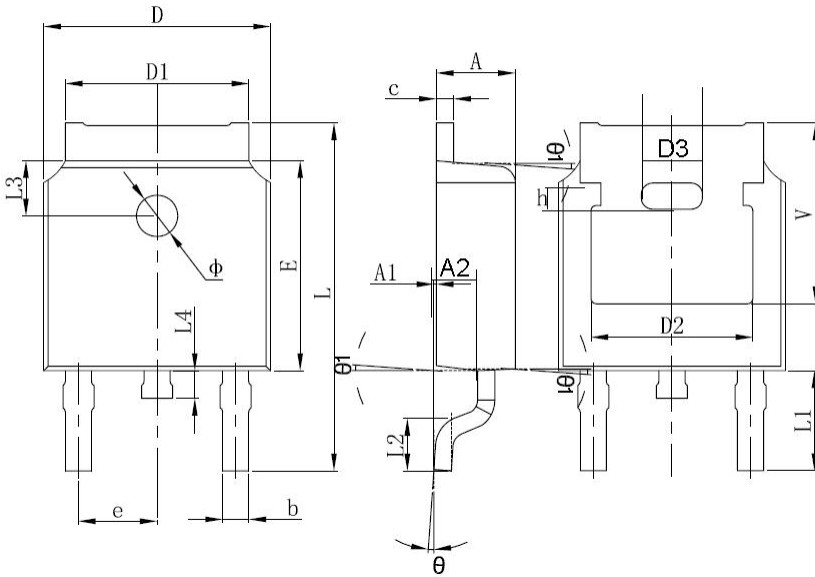
- **Case:** Molded Plastic
- **Terminals:** Solder Plated , Solderable Per MIL-STD 750, Method 2026
- **Weight:** 0.39 grams(Approx)

Maximum Ratings and Electrical Characteristics @ $T_A=25^{\circ}\text{C}$ unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	SDD660	Units
Maximum Peak Repetitive Reverse Voltage Maximum DC Blocking Voltage	V_{RRM} V_R	600	V
Maximum RMS Voltage	V_{RMS}	420	
Maximum Average Forward Rectified Current 0.375"(9.5mm) Lead Length @ $T_C = 105^{\circ}\text{C}$	$I_{(AV)}$	6.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	70	A
Maximum Instantaneous Forward Voltage @ $I_F = 6.0\text{A}$	V_F	1.1	V
Maximum DC Reverse Current At Rated DC Blocking Voltage @ $T_A = 25^{\circ}\text{C}$	I_R	5	μA
Maximum Thermal Resistance Junction to Case	$R_{\theta JC}$	5	$^{\circ}\text{C}/\text{W}$
Operating Storage Temperature Range	T_{STG}	-55 to +150	$^{\circ}\text{C}$
Operating Junction Temperature	T_J	-55 to +150	$^{\circ}\text{C}$

Mechanical Dimensions DPAK



SYMBOL	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.20	2.40	0.087	0.094
A1	0.00	0.127	0.000	0.005
b	0.66	0.86	0.026	0.034
c	0.46	0.60	0.018	0.024
D	6.50	6.70	0.256	0.264
D1	5.13	5.46	0.202	0.215
D2	4.83 REF.		0.190 REF.	
E	6.00	6.20	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.70	10.40	0.381	0.409
L1	2.90 REF.		0.144 REF.	
L2	1.40	1.70	0.055	0.067
L3	1.60 REF.		0.063 REF.	
L4	0.60	1.00	0.024	0.039
Φ	1.10	1.30	0.043	0.051
Θ	0°	8°	0°	8°
h	0.00	0.30	0.000	0.012
V	5.35 REF.		0.211 REF.	

Ordering Information

Device	Package	Shipping
SDD660	DPAK (Pb-Free)	2500pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram

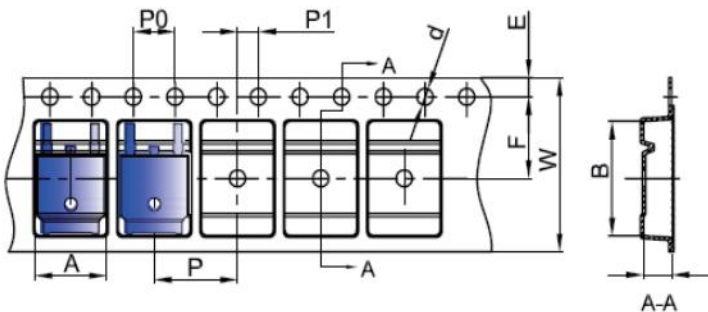


Where XXXXX is YYWWL

SDD660 = Part Name
SSG = SSG
YY = Year
WW = Week
L = Lot Number

Cautions: Molding resin
Epoxy resin UL:94V-0

Carrier Tape Specification DPAK



SYMBOL	Millimeters	
	Min.	Max.
A	6.80	7.00
B	10.40	10.60
C	2.60	2.80
d	Φ1.45	Φ1.65
E	1.65	1.85
F	7.40	7.60
P0	3.90	4.10
P	7.90	8.10
P1	1.90	2.10
W	15.90	16.30

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